

Appl. No. : 09/389,720  
 Filed : September 3, 1999

The Examiner also objected to the drawings of Claims 24, 25 and 29. Applicant has cancelled Claim 25.

As to Claim 24, FIG. 2 shows a lead-over-chip (LOC) 17. Applicant believes that leads do not have to be shown in the drawing to support Claim 24. Thus, Applicant respectfully requests the Examiner to reevaluate his objection.

As to Claim 29, FIGS. 2 and 3 show that each one of the substrate units 24 includes a pair of adhesive tabs 48. Thus, Applicant respectfully requests the Examiner to withdraw his objection.

### **CONCLUSION**

In view of the forgoing, the present application is believed to be in condition for allowance, and such allowance is respectfully requested. If further issues remain to be resolved, the Examiner is cordially invited to contact the undersigned such that any remaining issues may be promptly resolved. Also, please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

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**VERSION WITH MARKING TO SHOW CHANGES MADE**

**IN THE CLAIMS:**

Claims 1-19, 25, 28 and 31-34 have been cancelled.

Claim 20 has been amended as follows:

20. (AMENDED) An assembly, comprising:

a film including a plurality of substrate units with each of said plurality of  
substrate units being adapted to electrically interface with a [plurality of dies]corresponding die,  
each one of said plurality of substrate units being generally defined on said film between a pair  
of flanking slots; and

a carrier in mechanical communication with said film for providing enhanced  
rigidity to said film by being sized and configured to add material at selected regions of said  
film.